
HD74HC244

Octal Buffers/Line Drivers/Line Receivers
(with noninverted 3-state outputs)

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Description

The HD74HC244 is a non-inverting buffer and has two active low enables ($\overline{1G}$ and $\overline{2G}$). Each enable independently controls 4 buffers.

This device does not have schmitt trigger inputs.

Features

- High Speed Operation: $t_{pd} = 11$ ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

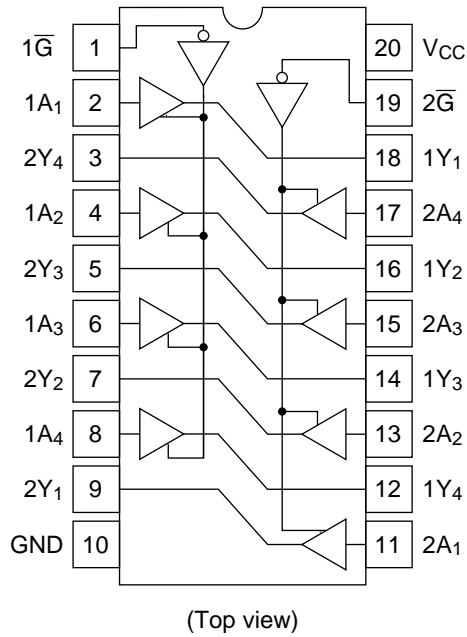
Function Table

Inputs		Output
\overline{G}	A	Y
H	X	Z
L	H	H
L	L	L

Notes H: high level
L: low level
X: irrelevant
Z: off (high-impedance) state of a 3-state output

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Pin Arrangement

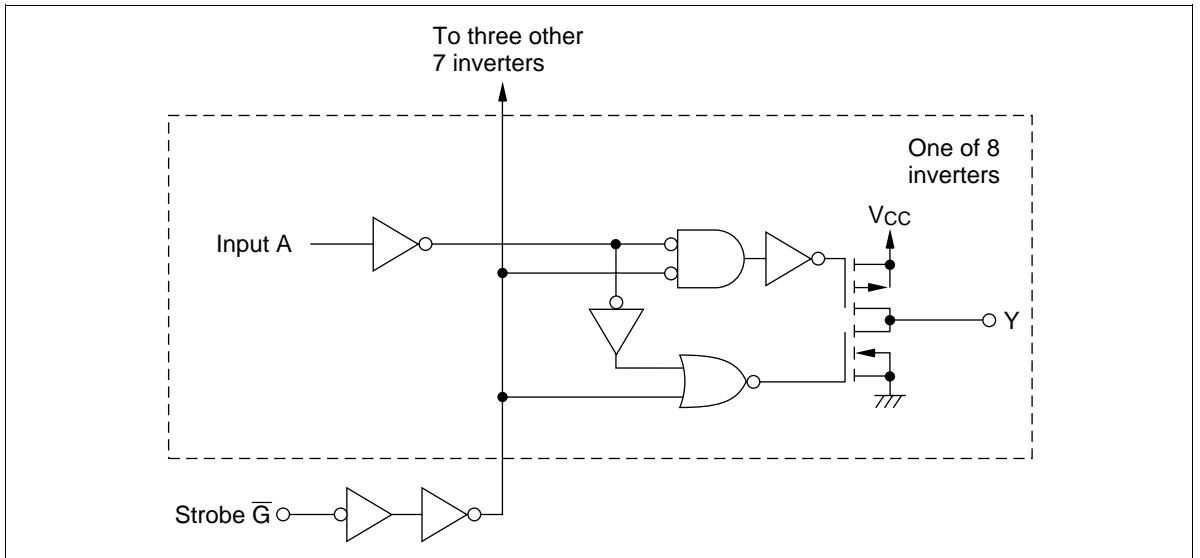


Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage range	V_{CC}	-0.5 to +7.0	V
Input voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
Output voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
DC current drain per pin	I_{OUT}	± 35	mA
DC current drain per V_{CC} , GND	I_{CC} , I_{GND}	± 75	mA
DC input diode current	I_{IK}	± 20	mA
DC output diode current	I_{OK}	± 20	mA
Power Dissipation per package	P_T	500	mW
Storage temperature	Tstg	-65 to +150	°C

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Logic Diagram

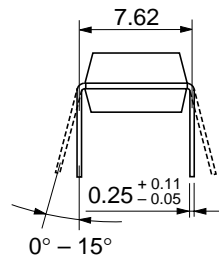
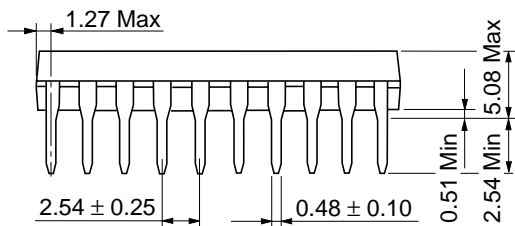
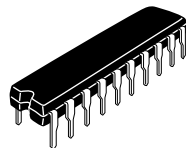


DC Characteristics

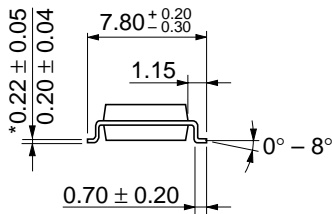
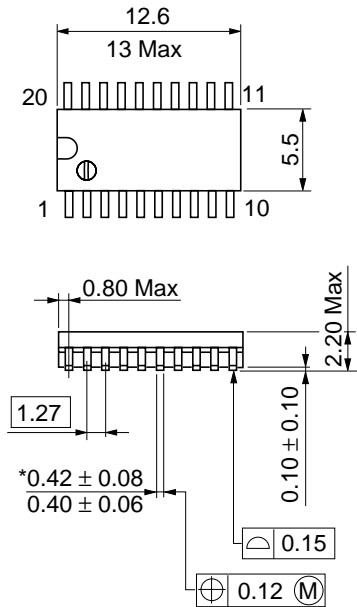
Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V _{IL}	2.0	—	—	0.5	—	0.5		V
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		I _{OH} = -6 mA
		6.0	5.68	—	—	5.63	—		I _{OH} = -7.8 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		I _{OL} = 6 mA
		6.0	—	—	0.26	—	0.33		I _{OL} = 7.8 mA
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40 \text{ to } +85^\circ\text{C}$		Unit	Test Conditions
			Min	Typ	Max	Min		
Propagation delay time	t_{PHL}	2.0	—	—	90	—	115	ns
		4.5	—	12	18	—	23	
		6.0	—	—	15	—	20	
	t_{PLH}	2.0	—	—	90	—	115	ns
		4.5	—	10	18	—	23	
		6.0	—	—	15	—	20	
Output enable time	t_{ZL}	2.0	—	—	150	—	190	ns
		4.5	—	11	30	—	38	
		6.0	—	—	26	—	33	
	t_{ZH}	2.0	—	—	150	—	190	ns
		4.5	—	12	30	—	38	
		6.0	—	—	26	—	33	
Output disable time	t_{LZ}	2.0	—	—	150	—	190	ns
		4.5	—	16	30	—	38	
		6.0	—	—	26	—	33	
	t_{HZ}	2.0	—	—	150	—	190	ns
		4.5	—	19	30	—	38	
		6.0	—	—	26	—	33	
Output rise/fall time	t_{TLH}	2.0	—	—	60	—	75	ns
	t_{THL}	4.5	—	4	12	—	15	
		6.0	—	—	10	—	13	
Input capacitance	C_{in}	—	—	5	10	—	10	pF

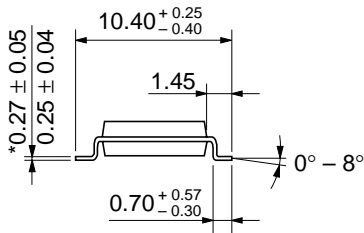
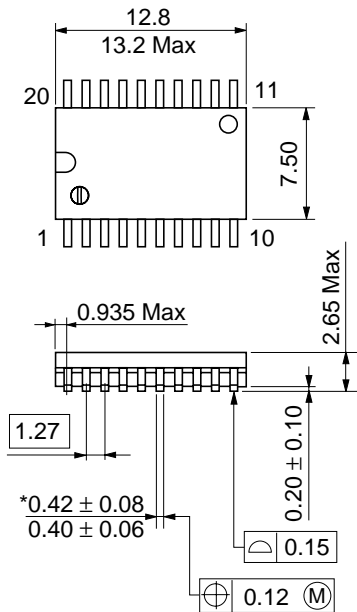


Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Weight (reference value)	1.26 g



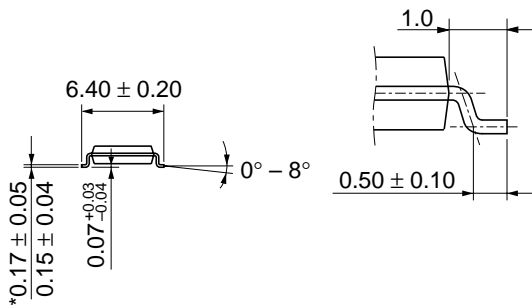
Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.31 g

*Dimension including the plating thickness
Base material dimension



Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Weight (reference value)	0.52 g

*Dimension including the plating thickness
 Base material dimension



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-20DA
JEDEC	—
EIAJ	—
Weight (reference value)	0.07 g

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